

Appl. No. : Unknown
 Filed : Herewith

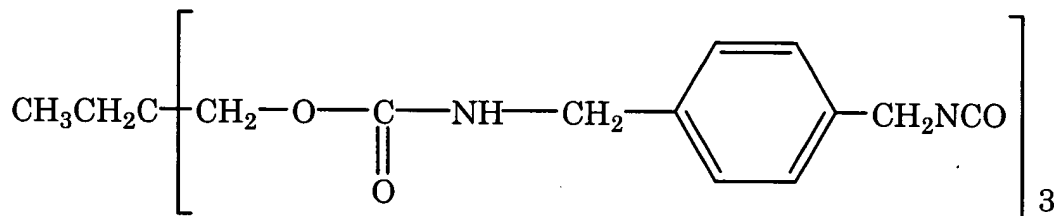
AMENDMENTS TO THE CLAIMS

Please amend the Claims as follows. Insertions are shown underlined while deletions are ~~struck through~~.

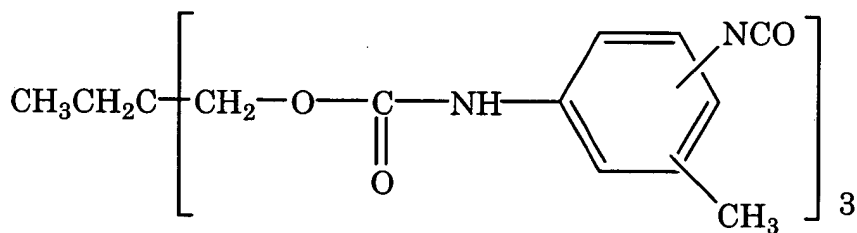
1 (currently amended): An adhesive composition comprising epoxy resins (A), phenol resins (B), synthetic rubber (C), and microcapsules (D), ~~including the hardening accelerator that~~ has each microcapsule having a core/shell structure in which a core part including ~~the~~ a hardening accelerator is covered by a shell part formed with thermoplastic resins.

2 (currently amended): The adhesive composition according to Claim 1, wherein ~~at the~~ a shell part of the microcapsule (D) including the hardening accelerator is formed with a polyurea having an isocyanate compound using a triisocyanate compound (1) represented with following chemical formula (1), and a triisocyanate compound (2) represented with following chemical formula (2) at a percentage of a mixed molar ratio of (compound (1)) / (compound (2)) = 100 / 0 - 30 / 70 as a constituent element.

Chemical formula -- (1)



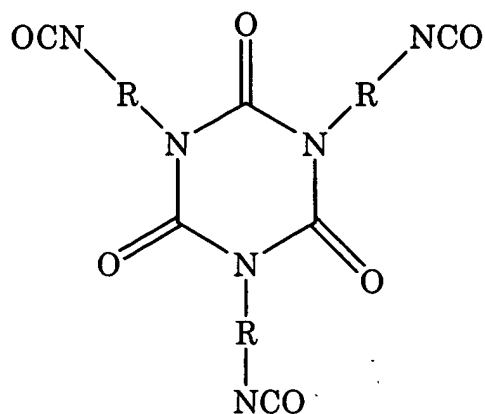
Chemical formula -- (2)



3 (currently amended): The adhesive composition according to Claim 1, wherein ~~at the~~ a shell part of the microcapsule (D) including the hardening accelerator is formed with a polyurea having a triisocyanate compound (3) represented with following general formula (3) as a constituent element, ~~(where, wherein R represents a bivalent organic group in the general formula (3)) as a constituent element.~~

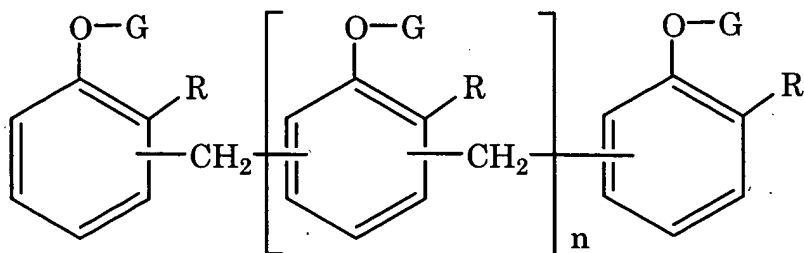
Chemical formula -- (3)

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4 (currently amended): The adhesive composition according to Claim 1, wherein the epoxy resin (A) has a novolak type epoxy resin represented with the following general formula (4) as a principal component (~~where, wherein~~ G represents a glycidyl group, R represents -H or -CH₃, and n represents an integer of 1 or more ~~in the general formula (4)) as a principal component~~).

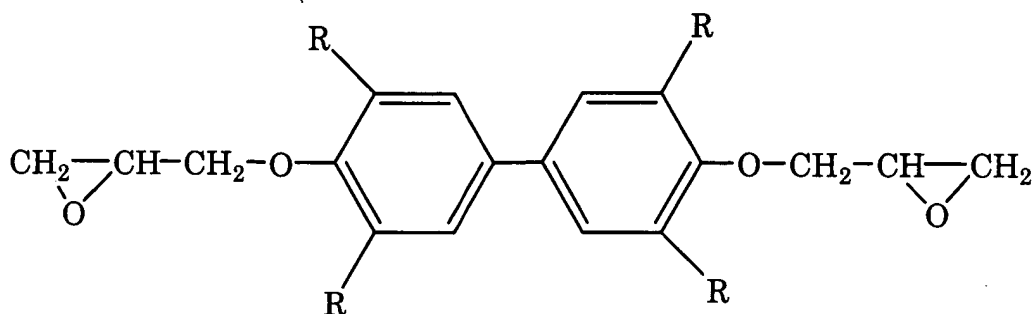
Chemical formula -- (4)



5 (currently amended): The adhesive composition according to Claim 1, wherein the epoxy resin (A) has a biphenyl type epoxy resin represented with the following general formula (5) as a principal component, (~~where, wherein~~ R represents -H or -CH₃ ~~in the general formula (5)) as a principal component~~).

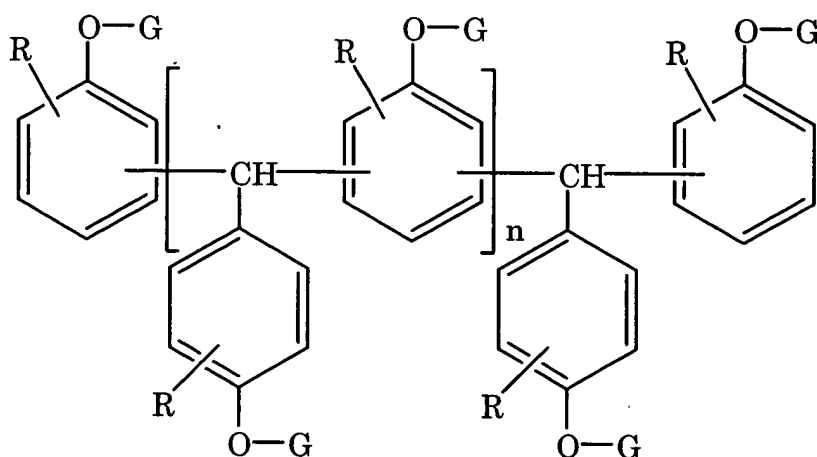
Chemical formula -- (5)

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6 (currently amended): The adhesive composition according to Claim 1, wherein the epoxy resin (A) has a tris hydroxyphenylmethane type epoxy resin represented with at the following general formula (6) as a principal component, ~~(where, wherein~~ G represents a glycidyl group, R represents -H or -CH₃, and n represents zero or an integer of 0 or 1 or more ~~in the~~ general formula (6)) as a principal component.

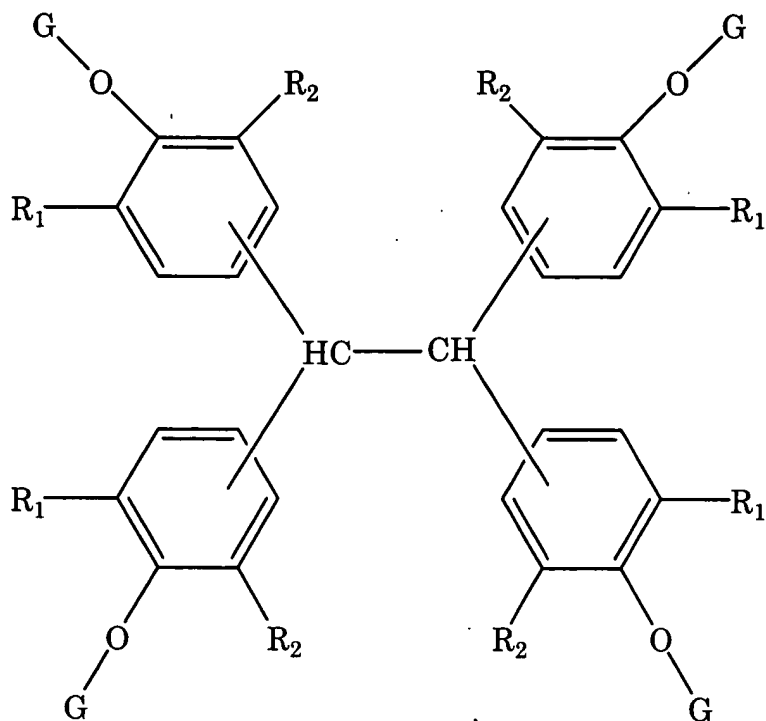
Chemical formula -- (6)



7 (currently amended): The adhesive composition according to Claim 1, wherein the epoxy resin (A) has a tetraphenylol ethane type epoxy resin represented with at the following general formula (7) as a principal component, ~~(where, wherein~~ G represents a glycidyl group, and R₁ and R₂ each represent independently represent -H or -CH₃, ~~respectively, in the general~~ formula (7)) as a principal component.

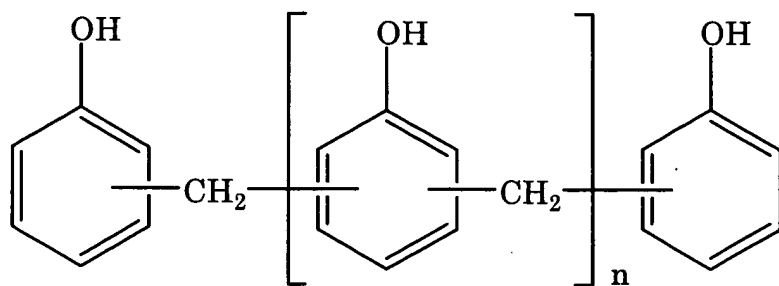
Chemical formula -- (7)

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8 (currently amended): The adhesive composition according to Claim 1, wherein the phenol resin (B) is a phenol novolak resin represented with the following general formula (8), ~~(where, wherein n represents zero or an integer of 0 or 1 or more in the general formula (8)).~~

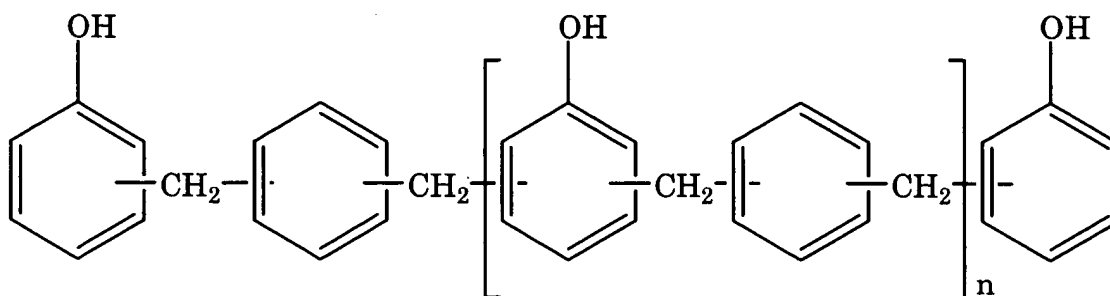
Chemical formula -- (8)



9 (currently amended): The adhesive composition according to Claim 1, wherein the phenol resin (B) is a phenol aralkyl resin represented with the following general formula (9), ~~(where, wherein, n represents zero or an integer of 0 or 1 or more in the general formula (9)).~~

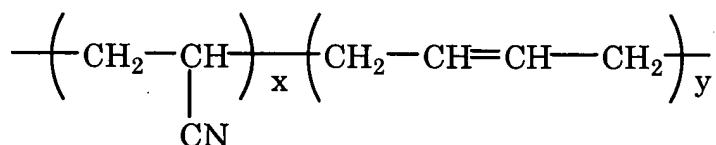
Chemical formula -- (9)

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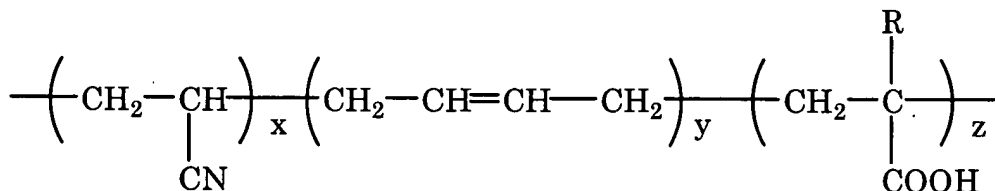
10 (currently amended): The adhesive composition according to Claim 1, wherein the synthetic rubber (C) is an acrylonitrile-butadiene rubber having a repeating unit represented with the following general formula (10) as a principal constituent element, ~~(where, wherein x : y = 1 - 99 : 1 - 99 in the general formula (10))~~ as a principal constituent element.

Chemical formula -- (10)



11 (currently amended): The adhesive composition according to Claim 1, wherein the synthetic rubber (C) is a carboxylated acrylonitrile-butadiene rubber having a repeating unit represented with the following general formula (11) as a principal constituent element, ~~(where, wherein R represents -H or -CH₃, and x : y : z = 1 - 98 : 1 - 98 : 1 - 98 in the general formula (11))~~ as a principal constituent element.

Chemical formula -- (11)

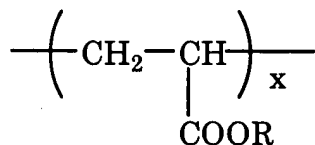


12 (currently amended): The adhesive composition according to Claim 1, wherein the synthetic rubber (C) is a carboxylated acrylic rubber having a repeating unit represented with the following general formula (12) as a principal constituent element, ~~(where, wherein R represents a~~

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monovalent organic group, and x represents an integer of 1 or more in the general formula (12)) as a principal constituent element.

Chemical formula -- (12)



13 (currently amended): The adhesive composition according to Claim 1, wherein further comprising inorganic fillers ~~are further included~~.

14 (original): An adhesive film being formed of the adhesive composition according to Claim 1.

15 (original): A laminated adhesive film comprising the adhesive film according to Claim 14 and a pressure sensitive adhesive film.

16 (currently amended): ~~An~~ The adhesive film according to Claim 14 which is configured for die bonding a semiconductor device using the adhesive film according to Claim 14 or 15.

17 (original): A semiconductor apparatus wherein a semiconductor device is die-bonded using the adhesive film for die bonding according to Claim 16.

18 (new): The laminated adhesive film according to Claim 15 which is configured to die bond a semiconductor device.

19 (new): A semiconductor apparatus wherein a semiconductor device is die-bonded using the laminated adhesive film for die bonding according to Claim 18.